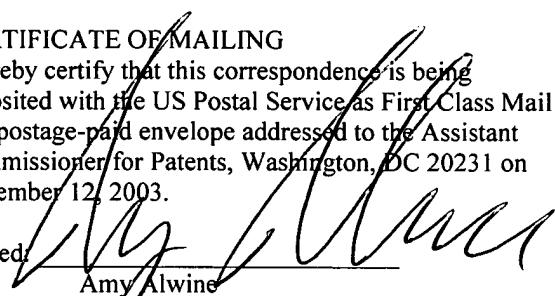




IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<p>Re application of: Basol et al. Serial No.: 10/663,318 Filed: September 16, 2003 Title: Conductive Structure Fabrication Process Using Novel Layered Structure And Conductive Structure Fabricated Thereby For Use In Multi-Level Metallization</p>	<p>Group Art Unit: Not yet assigned Examiner: Not yet assigned Docket: NT-108C1-US</p> <p>CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the US Postal Service as First Class Mail in a postage-paid envelope addressed to the Assistant Commissioner for Patents, Washington, DC 20231 on November 12, 2003.</p> <p>Signed:  Amy Alwine</p>
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INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Trademarks
Washington, D.C. 20231

Dear Sir:

Applicants submit information herewith to comply with the obligations set forth in 37 CFR §1.56. A copy of an International Search Report dated June 27, 2001 is also submitted. These submissions are not an admission that any of the documents are prior art or otherwise relevant to the subject application.

This IDS is submitted:

- with a filed patent application or within 3 months of the US application filing date;
- before the mailing of a first office action on the merits;
- after the first office action, but prior to a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) or a certification set forth below; or
- after a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) and a certification set forth below, where this submission is a petition requesting consideration of this IDS.

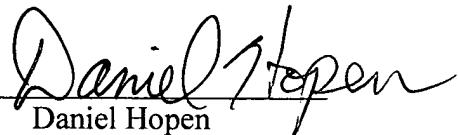
If identified above, Applicant certifies that:

- the information was first cited in a communication from a foreign patent office in a counterpart foreign application less than 3 months prior to this IDS; or

[] to the knowledge of the person signing this certification after making reasonable inquiry, the information was not known to any individuals designated in 37 CFR §1.56 more than 3 months prior to this IDS.

If any matters can be resolved by telephone, Applicant requests that the Patent and Trademark Office call the Applicant at the telephone number listed below.

Respectfully submitted,

By: 
Daniel Hopen
Reg. No. 35,547

NuTool, Inc.
Legal Department
1655 McCandless Drive
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(408) 586-9500x268



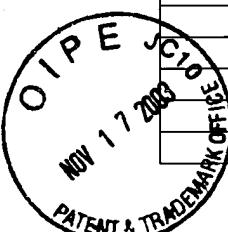
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INFORMATION DISCLOSURE STATEMENT

US PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	
	AA	6,191,027	Feb., 2001	Omura	In Serial No. 09/642,827
	AB	6,176,992	January, 2001	Talieh	In Serial No. 09/642,827
	AC	6,136,163	October, 2000	Cheung et al.	In Serial No. 09/642,827
	AD	6,103,085	August, 2000	Woo et al.	In Serial No. 09/642,827
	AE	6,074,544	June, 2000	Reid et al.	In Serial No. 09/642,827
	AF	6,066,030	May, 2000	Uzoh	In Serial No. 09/642,827
	AG	6,063,506	May, 2000	Andricacos et al.	In Serial No. 09/642,827
	AH	6,027,631	February, 2000	Broadbent	In Serial No. 09/642,827
	AI	6,004,880	December, 1999	Liu et al.	In Serial No. 09/642,827
	AJ	5,985,123	November, 1999	Koon	In Serial No. 09/642,827
	AK	5,954,997	September, 1999	Kaufman et al.	In Serial No. 09/642,827
	AL	5,933,753	August, 1999	Simon et al.	In Serial No. 09/642,827
	AM	5,930,669	July, 1999	Uzoh	In Serial No. 09/642,827
	AN	5,922,091	July, 1999	Tsai et al.	In Serial No. 09/642,827
	AO	5,911,619	June, 1999	Uzoh et al.	In Serial No. 09/642,827
	AP	5,897,375	April, 1999	Watts et al.	In Serial No. 09/642,827
	AQ	5,884,990	March, 1999	Burghartz et al.	In Serial No. 09/642,827
	AR	5,858,813	January, 1999	Scherber et al.	In Serial No. 09/642,827
	AS	5,840,629	November, 1998	Carpio	In Serial No. 09/642,827
	AT	5,807,165	September, 1998	Uzoh et al.	In Serial No. 09/642,827
	AU	5,795,215	August, 1998	Guthrie et al.	In Serial No. 09/642,827
	AV	5,793,272	August, 1998	Burghartz et al.	In Serial No. 09/642,827
	AW	5,773,364	June, 1998	Farkas et al.	In Serial No. 09/642,827
	AX	5,770,095	June, 1998	Sasaki et al.	In Serial No. 09/642,827
	AY	5,762,544	June, 1998	Zuniga et al.	In Serial No. 09/642,827
	AZ	5,755,859	May, 1998	Brusic et al.	In Serial No. 09/642,827
	BA	5,681,215	October, 1997	Sherwood et al.	In Serial No. 09/642,827
	BB	5,516,412	May, 1996	Andricacos et al.	In Serial No. 09/642,827
	BC	5,354,490	October, 1994	Yu et al.	In Serial No. 09/642,827
	BD	5,256,565	October, 1994	Bernhardt et al.	In Serial No. 09/642,827



	BE	5,084,071	January, 1992	Nenadic et al.	In Serial No. 09/642,827
	BF	4,975,159	December, 1990	Dahms	In Serial No. 09/642,827
	BG	4,954,142	September, 1990	Carr et al.	In Serial No. 09/642,827
	BH	4,948,474	August, 1990	Miljkovic	In Serial No. 09/642,827
	BI	4,430,173	February, 1984	Boudot et al.	In Serial No. 09/642,827
	BJ	3,328,273	June, 1967	Creutz et al.	In Serial No. 09/642,827

FOREIGN PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant		
BK	PCT 98/27585		June, 1998	Deligianni et al.	In Serial No. 09/642,827	
BL	WO 00/26443		May, 2000	Talieh	In Serial No. 09/642,827	

OTHER DOCUMENTS

Examiner Initials	Cite No.		Trans-lation
BM	James J. Kelly et al., "Leveling and Microstructural Effects of Additives for Copper Electrodeposition", Journal of the Electrochemical Society, 146 (7), 1999, Pages 2540-2545	In Serial No. 09/642,827	
BN	Joseph M. Steigerwald et al., "Chemical Mechanical Planarization of Microelectronic Materials", A Wiley-Interscience Publication, 1997 by John Wiley & Sons, Inc. pages 212-222.	In Serial No. 09/642,827	
BO	Robert D. Mikkola et al., "Investigation of the Roles of the Additive Components for Second Generation Copper Electroplating Chemistries Used for Advanced Interconnect Metalization", 2000 IEEE, IEEE Electron Devices Society, Pages 117-119, June 2000	In Serial No. 09/642,827	

Examiner Signature		Date Considered	
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